

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MOTOMU KURATA	03/25/2016
SHINYA SASAGAWA	03/28/2016
RYOTA HODO	03/25/2016
YUTA IIDA	03/25/2016
SATORU OKAMOTO	03/25/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.
<b>Street Address:</b>	398, HASE
<b>City:</b>	ATSUGI-SHI, KANAGAWA-KEN
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	243-0036
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15092973
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	12732-1675001
<b>NAME OF SUBMITTER:</b>	JANELLE A. JACKSON
<b>SIGNATURE:</b>	/Janelle A. Jackson/
<b>DATE SIGNED:</b>	04/13/2016
<b>Total Attachments: 2</b>	

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ASSIGNMENT

For valuable consideration, We, Motomu KURATA of Isehara, Kanagawa, Japan, Shinya SASAGAWA of Chigasaki, Kanagawa, Japan, Ryota HODO of Atsugi, Kanagawa, Japan, Yuta IIDA of Atsugi, Kanagawa, Japan and Satoru OKAMOTO of Isehara, Kanagawa, Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd., a Japanese corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled METHOD FOR FABRICATING ELECTRODE AND SEMICONDUCTOR DEVICE, filed April 7, 2016, and assigned U.S. Serial Number 15/092,973, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature Motomu Kurata  
Name: Motomu KURATA  
Date: 03/25/2016

Signature Shinya Sasagawa  
Name: Shinya SASAGAWA  
Date: 03/28/2016

Signature Ryota Hodo  
Name: Ryota HODO  
Date: 03/25/2016

Signatur Yuta Iida  
Name: Yuta IIDA  
Date: 03/25/2016

Signatur Satoru Okamoto  
Name: Satoru OKAMOTO  
Date: 03/25/2016